

MEMORY MODULE

ABSTRACT

A memory module (20) comprising a base plate (21) and one or more embedding seats (30) formed thereon is provided for IC memory chip being installed in detachable manner, which base plate (21) has a plurality of printed circuit sets (22) each being in electric connection with a corresponding IC embedding seat (30); the structure of IC embedding seat (30) comprises a mainbody (40) and a sliding cover (50) formed a cover to the mainbody (40) with sliding movement to open or close the mainbody (40), and the mainbody (40) has one or more IC mounting compartments (41) for IC memory chip easily mounted and positioned in detachable manner or freely removed therefrom, which bottom of the IC mounting compartment (41) has a conducting pin array (45) formed by a plurality of conducting pin units (44) with elasticity and conductivity arrayed in matrix arrangement to form electric connection with the printed circuit set (22) of the base plate (21); the invented memory module (10) has the advantage of easy installation, convenient maintenance or replacement of IC memory chip as well as friendly effect in environmental protection, particularly, during IC maintenance and replacement, the defective IC memory chip can be simply and freely removed from the memory module (20), which does not need to process de-soldering with high temperature and shall prevent other good IC memory chip from damage due to high temperature, and which does not require using SMT, soldering paste or flux for IC maintenance and replacement and shall eliminate the bothering due to re-embedding the pads on IC memory chip and repositioning the IC memory chip.

Refer to Figure 2.



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